

	Type	Hits	Search Text
1	BRS	108	thin near1 film near1 overlay
2	BRS	36	(thin near1 film near1 overlay) and (optical photo)
3	BRS	47	(thin near1 film near1 overlay) and (optical light photo)
4	BRS	7	"5767568"
5	BRS	108	thin near1 film near1 overlay
6	BRS	36	(thin near1 film near1 overlay) and (optical photo)
7	BRS	7921	(thin near1 film) and (optical photo light) and cavity
8	BRS	1661	(thin near1 film) and (optical photo light) and (substrate with cavity)
9	BRS	945	(thin near1 film) and (optical photo light) and (substrate near4 cavity)
10	BRS	67	((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip bump ball) and ((bond bonding) adj pad)
11	BRS	63	((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo))
12	BRS	63	((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo))
13	BRS	675	(optical near1 (device receiver transmitter)) and (substrate with cavity)
14	BRS	0	((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<12121993
15	BRS	242	((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:04		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:07		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 09:35		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 09:35		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:05		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:05		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:08		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 10:57		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:10		
10	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/15 15:11		
11	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 10:32		
12	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:12		
13	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:07		
14	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:11		
15	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:53		

	Type	Hits	Search Text
16	BRS	241	((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))
17	BRS	16750	((thin near1 film) (flexible near2 interconnect\$3)) and (hdip hdi bump ball ((bond bonding) adj pad))
18	BRS	54	((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3)) and (hdip hdi bump ball ((bond bonding) adj pad))
19	BRS	11	
20	BRS	121	((sensitive sensor) near chip) and (substrate with cavity)
21	BRS	120	((sensitive sensor) near chip) and (substrate with cavity)) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3)) and (hdip hdi bump ball ((bond bonding) adj pad)))

	DBs	Time Stamp	Comments	Error Definition
16	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:12		
17	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:15		
18	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:06		
19	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:41		
20	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:18		
21	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 13:53		

	Type	Hits	Search Text
22	BRS	45	((((sensitive sensor) near chip) and (substrate with cavity)) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3)) and (hdip hdi bump ball ((bond bonding) adj pad)))) and @ad<19931212
23	BRS	100	((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3))
24	BRS	46	(((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3)) and (hdip hdi bump ball ((bond bonding) adj pad)))

	DBs	Time Stamp	Comments	Error Definition
22	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:09		
23	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:07		
24	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:07		

	DBs	Time Stamp	Comments	Error Definition
25	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:07		

	Type	Hits	Search Text
26	BRS	141	(((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3))))

	DBs	Time Stamp	Comments	Error Definition
26	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:35		

	Type	Hits	Search Text
27	BRS	141	<pre> (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo))) and ((thin near1 film) (flexible near2 interconnect\$3))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo))) and ((thin near1 film) (flexible near2 interconnect\$3))) not (((((optical near1 (device receiver transmitter))) </pre>

	DBs	Time Stamp	Comments	Error Definition
27	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:36		

	Type	Hits	Search Text
28	BRS	140	(((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3))) not (((((optical near1 (device receiver transmitter)) and (substrate with cavity)) and @ad<19931212) not (((thin near1 film) and (optical photo light) and (substrate near4 cavity)) and (hdip hdi bump ball) and ((bond bonding) adj pad)) not ((thin near1 film near1 overlay) and (optical photo)))) and ((thin near1 film) (flexible near2 interconnect\$3))) not (((((optical near1 (device receiver transmitter))
29	BRS	45	(optical near1 (device element receiver transmitter)) and (hdip hdi)
30	BRS	16	((optical near1 (device element receiver transmitter)) and (hdip hdi)) and @ad<19931212
31	BRS	109	((sensitive sensor) near chip) near3 optical

	DBs	Time Stamp	Comments	Error Definition
28	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 14:36		
29	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:08		
30	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:09		
31	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/02/19 16:19		